Product Change Notification - GBNG-05HZPN039

Date:
07 May 2020

Product Category:
16-Bit - Microcontrollers and Digital Signal Controllers; 32-bit Microcontrollers

Affected CPNs:

Notification subject:
CCB 4233 Final Notice: Qualification of MTAI as an additional assembly site for selected products available in 48L TQFP (7x7x1mm) package using palladium coated copper wire with gold flash (CuPdAu) bond wire

Notification text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open one of the icons found in the Affected CPNs section above.
NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MTAI as an additional assembly site for selected products available in 48L TQFP (7x7x1mm) package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

Pre Change:
Assembled at ANAP assembly site using AP4200 die attach, G631HQ molding compound, C194 lead frame material with 161x161 mils lead frame paddle size and MSL 3 classification

Post Change:
Assembled at ANAP assembly site using AP4200 die attach, G631HQ molding compound, C194 lead frame material with 161x161 mils lead frame paddle size and MSL 3 classification
Or
Assembled at MTAI assembly site using 3280 die attach, G700HA molding compound, C7025 lead frame material with 200 x 200 mils lead frame paddle size and MSL 1 classification

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (HQ) / MTAI
Wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	AP4200	AP4200	3280
Molding compound material	G631HQ	G631HQ	G700HA
Lead frame material	C194	C194	C7025
Lead frame paddle size	161x161 mils	161x161 mils	200 x 200 mils
MSL Classification	MSL 3	MSL 3	MSL 1

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MTAI as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

May 15, 2020 (date code: 2020)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	May 2020					
Workweek	18	19	20	21	22	23
Qual Report Availability		X				
Final PCN Issue Date		X				
Estimated Implementation Date			X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

May 07, 2020: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_GBNG-05HZPN039_Pre_and_Post_Change.pdf
PCN_GBNG-05HZPN039_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PIC24FJ256GA705-E/PT
PIC24FJ128GA705-E/PT
PIC24FJ64GA705-E/PT
PIC24FJ256GA705-I/PT
PIC24FJ128GA705-I/PT
PIC24FJ64GA705-I/PT
PIC24FJ256GA705T-I/PT
PIC24FJ128GA705T-I/PT
PIC24FJ64GA705T-I/PT
PIC32MM0064GPM048-E/PT
PIC32MM0128GPM048-E/PT
PIC32MM0256GPM048-E/PT
PIC32MM0064GPM048-I/PT
PIC32MM0128GPM048-I/PT
PIC32MM0256GPM048-I/PT
PIC32MM0256GPM048T-I/PT027
PIC32MM0256GPM048T-I/PT029
PIC32MM0256GPM048T-I/PT030
PIC32MM0064GPM048T-I/PT
PIC32MM0128GPM048T-I/PT
PIC32MM0256GPM048T-I/PT